

FDB14N30

N-Channel UniFET™ MOSFET

300 V, 14 A, 290 mΩ

Features

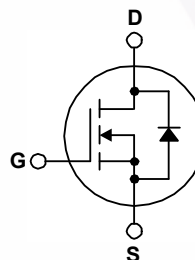
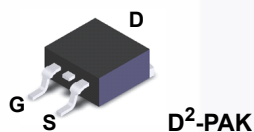
- $R_{DS(on)} = 290 \text{ m}\Omega$ (Max.) @ $V_{GS} = 10 \text{ V}$, $I_D = 7 \text{ A}$
- Low Gate Charge (Typ. 18 nC)
- Low C_{rss} (Typ. 17 pF)
- 100% Avalanche Tested
- Improved dv/dt Capability

Applications

- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

Description

UniFET™ MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter		FDB14N30TM	Unit
V_{DSS}	Drain-Source Voltage		300	V
I_D	Drain Current	- Continuous ($T_C = 25^\circ\text{C}$)	14	A
		- Continuous ($T_C = 100^\circ\text{C}$)	8.4	A
I_{DM}	Drain Current	- Pulsed (Note 1)	56	A
V_{GSS}	Gate-Source voltage		± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	330	mJ
I_{AR}	Avalanche Current	(Note 1)	14	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	14	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	140	W
		- Derate above 25°C	1.12	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	FDB14N30TM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.87	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max.	62.5	
	Thermal Resistance, Junction to Ambient (1 in ² pad of 2 oz copper), Max.	40	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB14N30	FDB14N30TM	D2-PAK	330mm	24mm	800 units

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	300	--	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	--	0.3	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 300V, V _{GS} = 0V V _{DS} = 240V, T _C = 125°C	-- --	-- --	1 10	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	3.0	--	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 7A	--	0.24	0.29	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 7A	--	10.5	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	815	1060	pF
C _{oss}	Output Capacitance		--	150	195	pF
C _{rss}	Reverse Transfer Capacitance		--	17	25	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 150V, I _D = 14A R _G = 25Ω (Note 4)	--	20	50	ns
t _r	Turn-On Rise Time		--	105	120	ns
t _{d(off)}	Turn-Off Delay Time		--	30	70	ns
t _f	Turn-Off Fall Time		--	75	160	ns
Q _g	Total Gate Charge	V _{DS} = 240V, I _D = 14A V _{GS} = 10V (Note 4)	--	18	25	nC
Q _{gs}	Gate-Source Charge		--	4.5	--	nC
Q _{gd}	Gate-Drain Charge		--	8	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	14	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	56	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 14A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 14A	--	235	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt =100A/μs	--	1.6	--	μC

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 2.8\text{mH}$, $I_{AS} = 14A$, $V_{DD} = 50V$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 14A$, $dI/dt \leq 200A/\mu s$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Characteristics

Figure 1. On-Region Characteristics

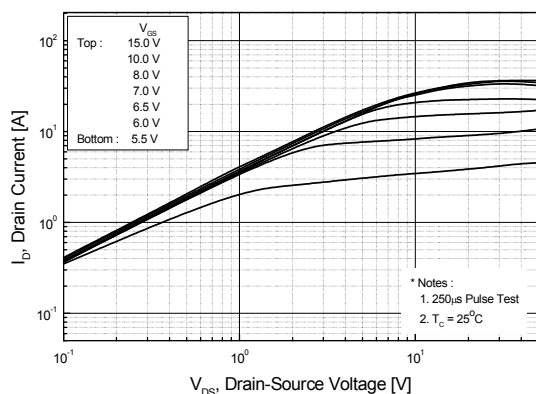


Figure 2. Transfer Characteristics

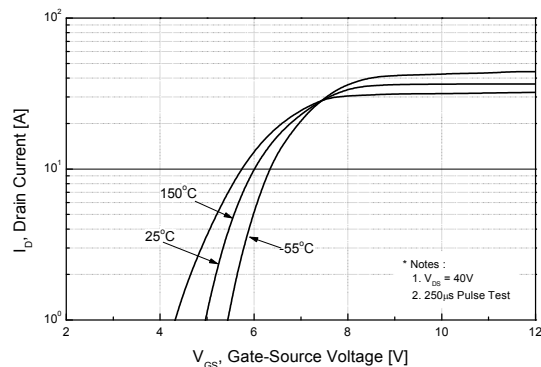


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

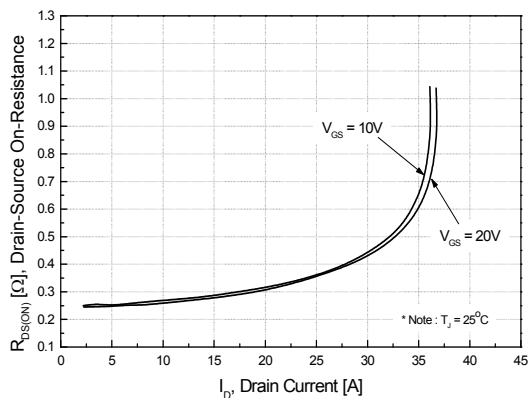


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

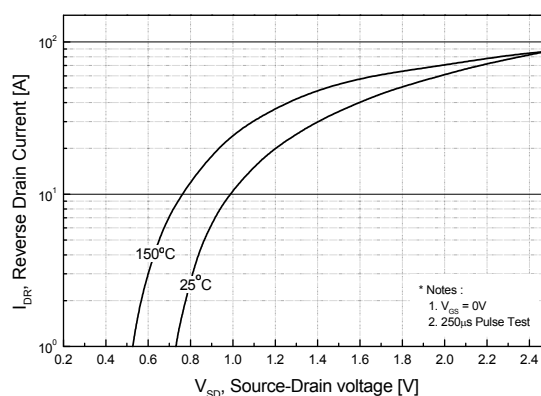


Figure 5. Capacitance Characteristics

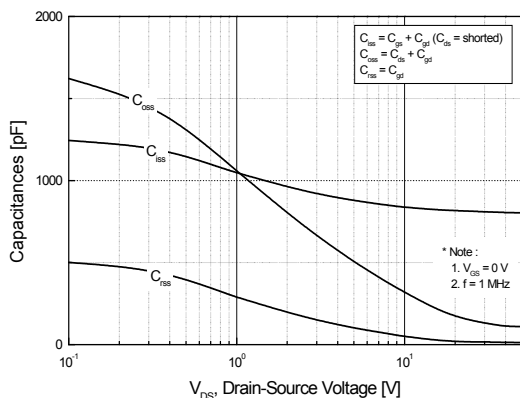
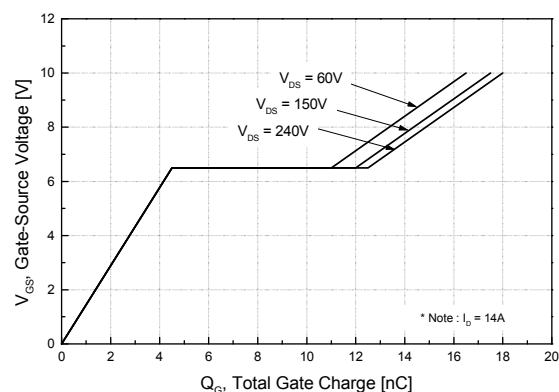


Figure 6. Gate Charge Characteristics



Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

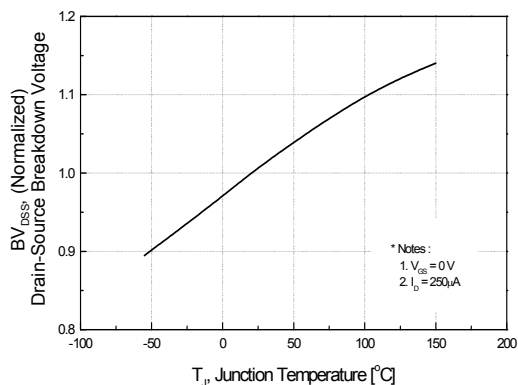


Figure 8. On-Resistance Variation vs. Temperature

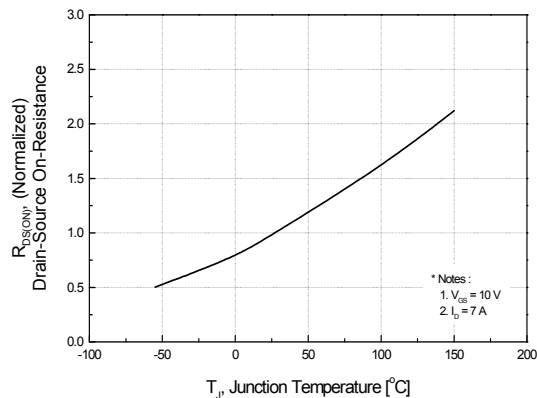


Figure 9. Maximum Safe Operating Area

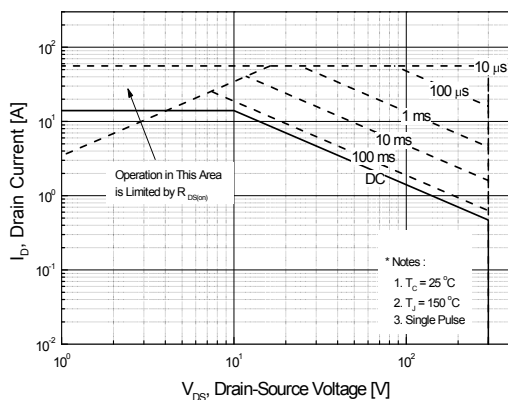


Figure 10. Maximum Drain Current vs. Case Temperature

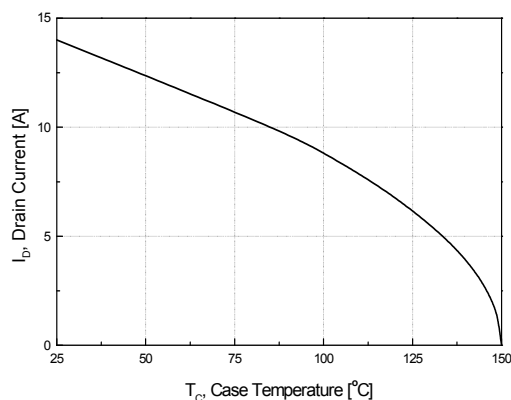


Figure 11. Transient Thermal Response Curve

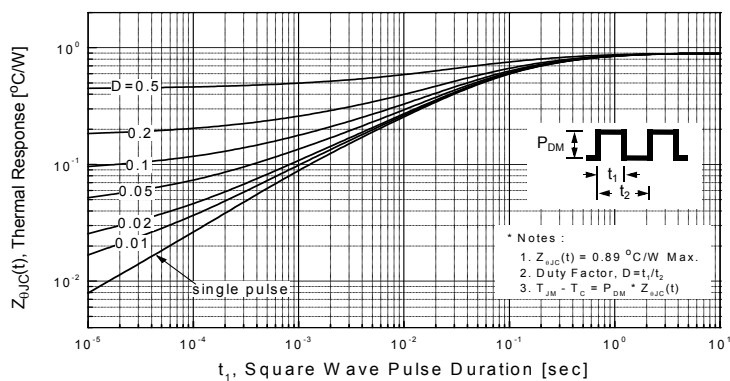


Figure 12. Gate Charge Test Circuit & Waveform

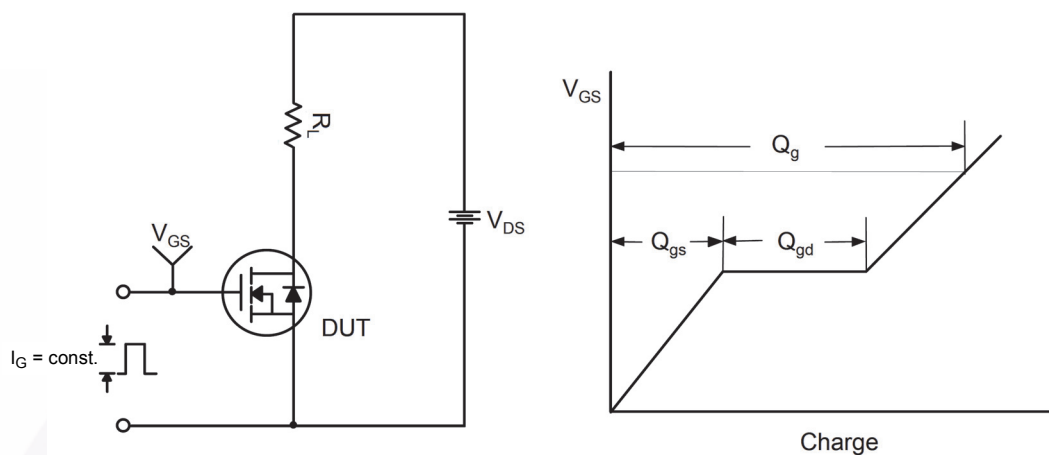


Figure 13. Resistive Switching Test Circuit & Waveforms

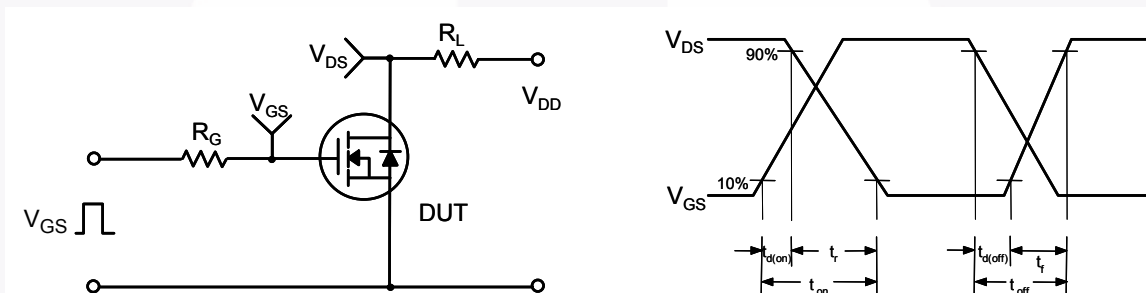


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

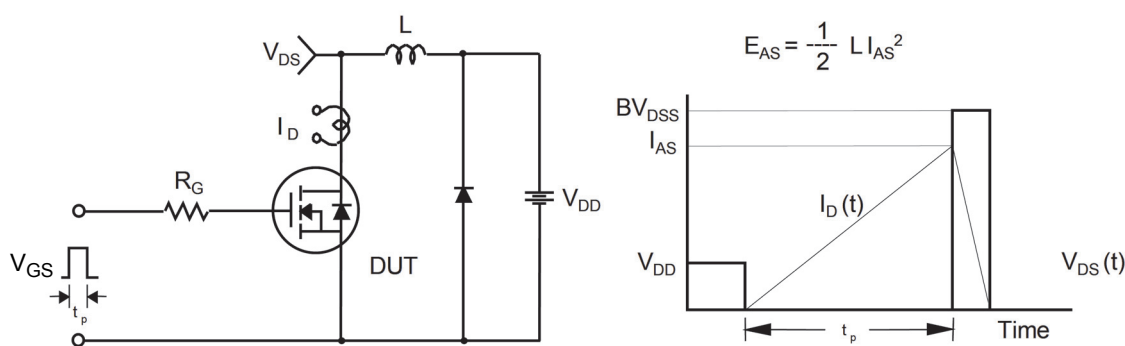
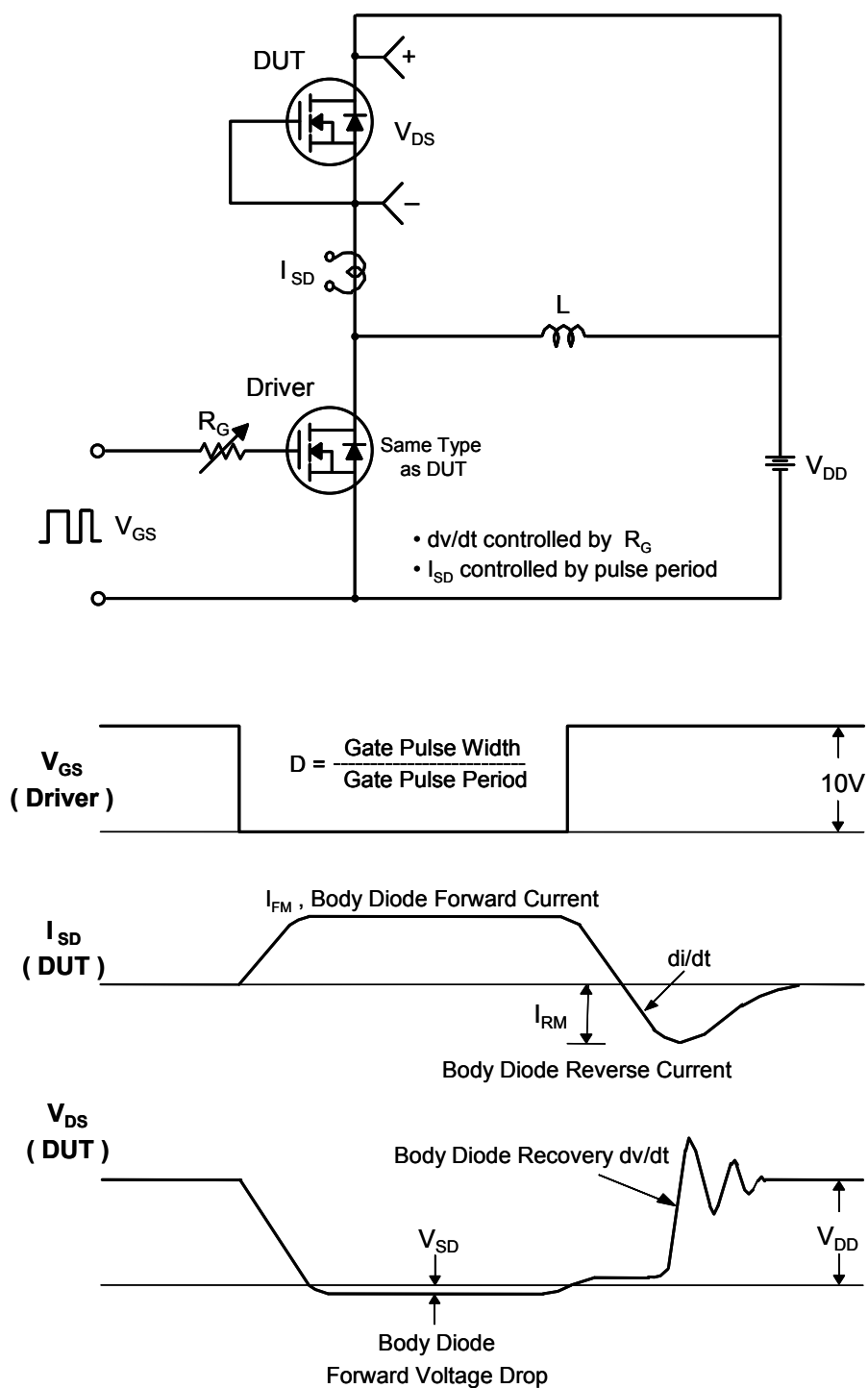


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

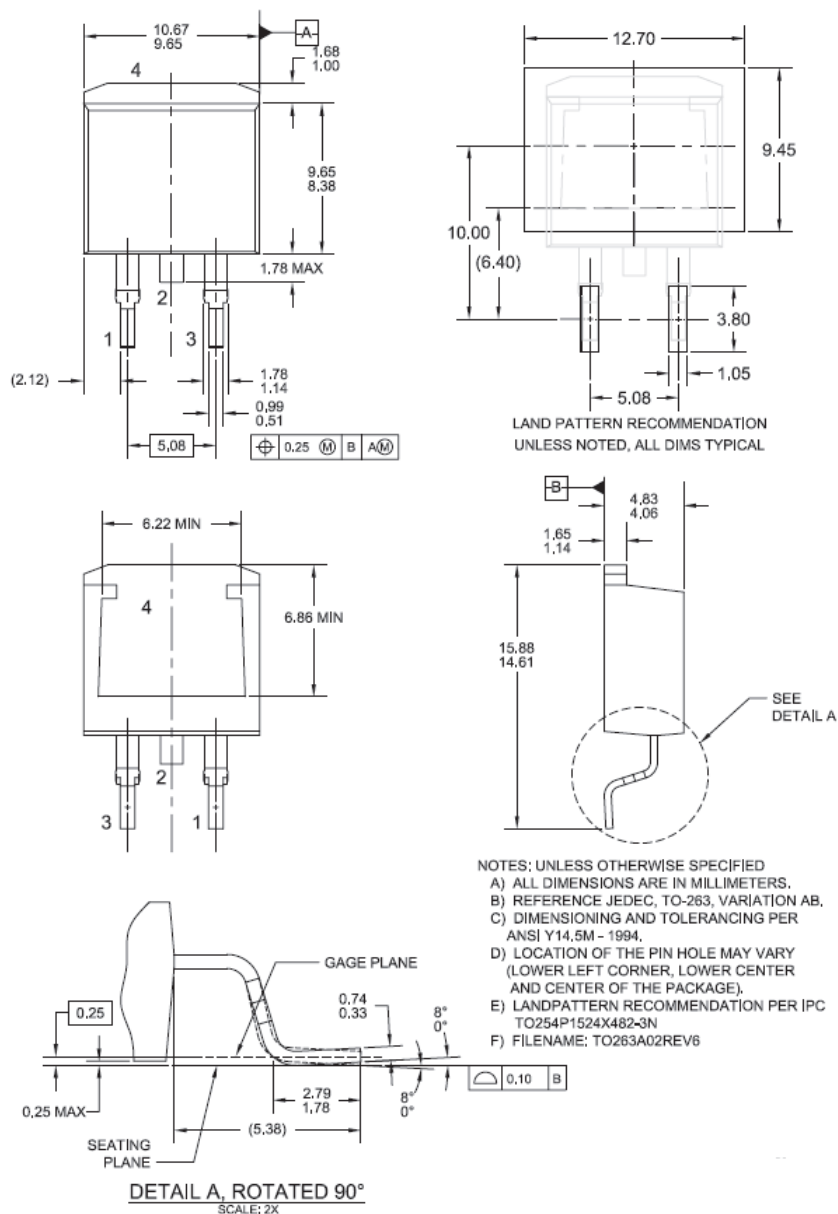
TO-263 2L (D²PAK)

Figure 16. 2LD, TO263, Surface Mount

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Dimension in Millimeters



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